

SOT906-3

plastic thermal enhanced very thin quad flat package; no leads; 88 terminals; body 10 x 10 x 0.85 mm

8 February 2016

Package information

1. Package summary

Terminal position code	Q (quad)
Package type descriptive code	HVQFN88
Package type industry code	HVQFN88
Package style descriptive code	HVQFN (thermal enhanced very thin quad flatpack; no leads)
Package style suffix code	NA (not applicable)
Package body material type	P (plastic)
Mounting method type	S (surface mount)
Issue date	21-3-2007

Table 1. Package summary

Symbol	Parameter	Min	Typ	Nom	Max	Unit
D	package length	9.9	-	10	10.1	mm
E	package width	9.9	-	10	10.1	mm
A	seated height	[tbd]	-	0.85	1	mm
A ₂	package height	[tbd]	-	0.85	[tbd]	mm
n ₂	actual quantity of termination	-	-	88	-	



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2. Package outline

HVQFN88: plastic thermal enhanced very thin quad flat package; no leads; 88 terminals; body 10 x 10 x 0.85 mm

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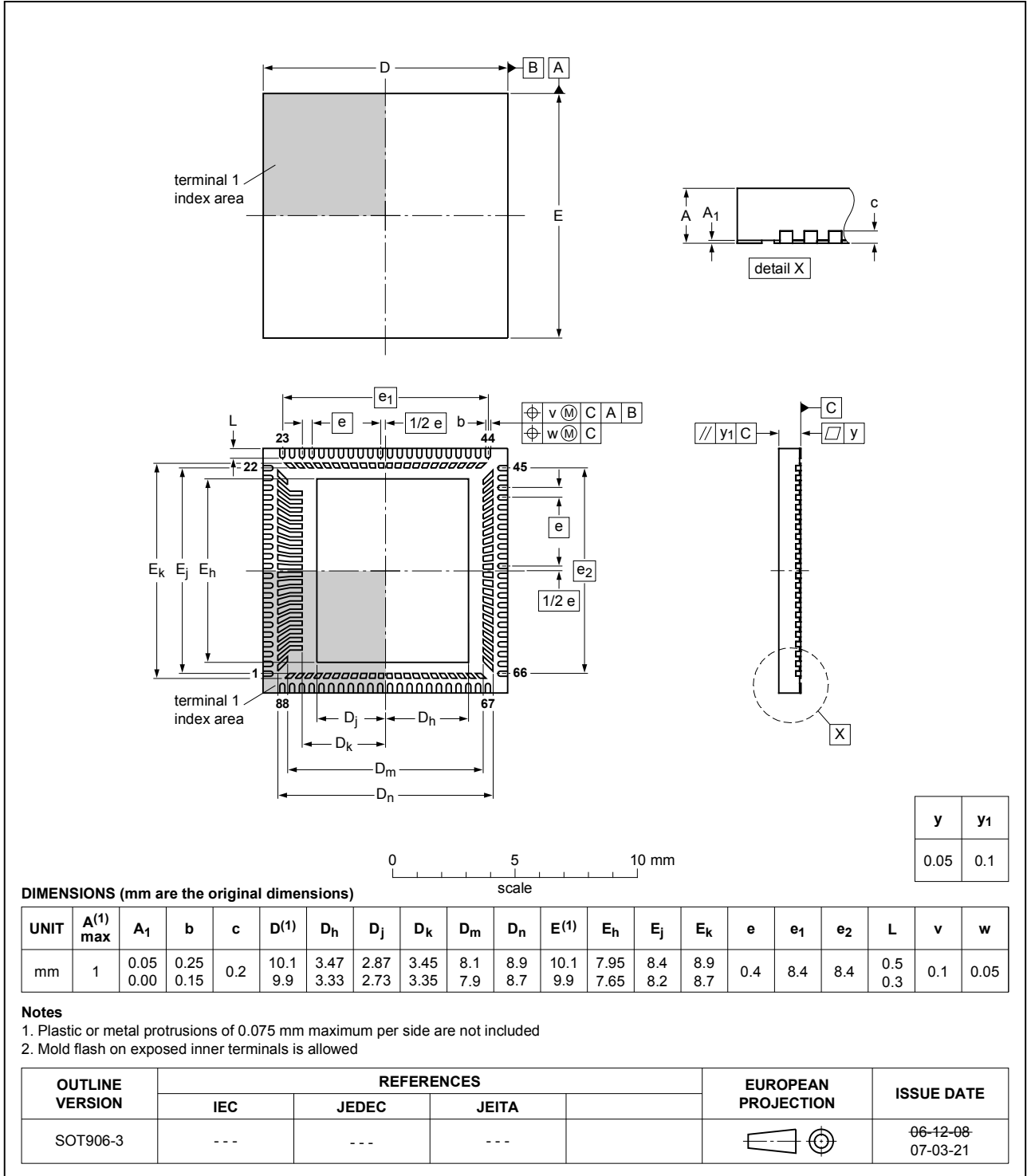


Fig. 1. Package outline HVQFN88 (SOT906-3)

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3. Soldering

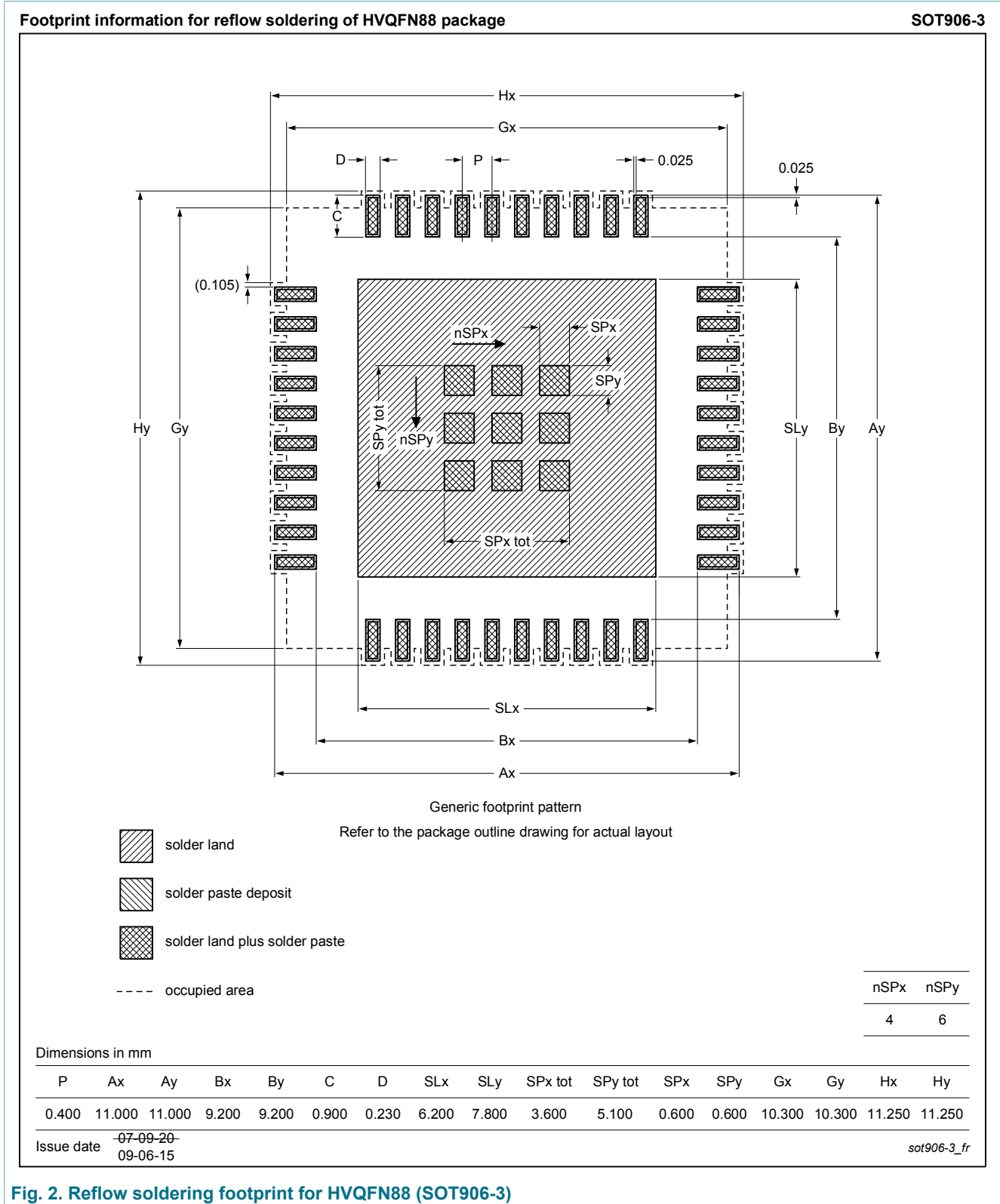


Fig. 2. Reflow soldering footprint for HVQFN88 (SOT906-3)

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4. Legal information

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